



Product Change Notification / JAON-13YWCO205

Date:

16-Jul-2020

Product Category:

8-bit Microcontrollers

PCN Type:

Manufacturing Change

Notification Subject:

CCB 3600.007 Final Notice: Qualification of MMT as an additional assembly site for selected Atmel products available in 40L PDIP package.

Affected CPNs:

[JAON-13YWCO205_Affected_CPN_07162020.pdf](#)

[JAON-13YWCO205_Affected_CPN_07162020.csv](#)

Notification Text:

PCN Status: Final notification

PCN Type: Manufacturing Change

Microchip Parts Affected: Please open one of the icons found in the Affected CPNs section above.

NOTE: For your convenience Microchip includes identical files in two formats (.pdf and .xls).

Description of Change: Qualification of MMT as an additional assembly site for selected Atmel products available in 40L PDIP package.

Pre Change:

Assembled at LPI assembly site using palladium coated copper with gold flash (CuPdAu) bond wire, CRM-1033BF die attach and G600 mold compound material or assembled at ASSH using palladium coated copper (PdCu) bond wire, EN-4900G die attach and CEL-9240 mold compound material.

Post Change:

Assembled at ASSH using palladium coated copper (PdCu) bond wire, EN-4900G die attach and CEL-9240 mold compound material or assembled at MMT assembly site using palladium coated copper with gold flash (CuPdAu) bond wire, CRM-1064L die attach and GE800 mold compound material.

Pre and Post Change Summary:

	Pre Change		Post Change	
Assembly Site	Lingsen Precision Industries, Taiwan (LPI)	ASE-Shanghai (ASSH)	ASE-Shanghai (ASSH)	Microchip Technology Thailand (Branch) - (MMT)
Wire material	CuPdAu	PdCu	PdCu	CuPdAu
Die attach material	CRM-1033BF	EN-4900G	EN-4900G	CRM-1064L
Molding compound material	G600	CEL-9240	CEL-9240	GE800
Lead frame material	CDA194	CDA194	CDA194	CDA194

Impacts to Data Sheet: None

Change Impact:None

Reason for Change:To improve on time delivery performance by qualifying MMT as an additional assembly site. Due to unforeseen business conditions the LPI location will be discontinued as an assembly site for 40L PDIP package.

Change Implementation Status:In Progress

Estimated First Ship Date:August 15, 2020 (date code: 2033)

NOTE: Please be advised that after the estimated first ship date customers may receive pre and post change parts.

Time Table Summary:

	July 2020					August 2020				
Workweek	27	28	29	30	31	32	33	34	35	36
Qual Report Availability			X							
Final PCN Issue Date			X							
Estimated Implementation Date							X			

Method to Identify Change: Traceability code

Qualification Report:Please open the attachments included with this PCN labeled as PCN_#_Qual Report.

Revision History: July 16, 2020: Issued final notification. Attached the qualification report. Provided estimated first ship date to be on August 15, 2020.

The change described in this PCN does not alter Microchip's current regulatory compliance regarding the material content of the applicable products.

Attachments:

[PCN_JAON-13YWCO205_Qual_Report.pdf](#)

Please contact your local [Microchip sales office](#) with questions or concerns regarding this notification.

Terms and Conditions:

If you wish to receive Microchip PCNs via email please register for our PCN email service at our [PCN home page](#) select register then fill in the required fields. You will find instructions about registering for Microchips PCN email service in the [PCN FAQ](#) section.

If you wish to change your PCN profile, including opt out, please go to the [PCN home page](#) select login and sign into your myMicrochip account. Select a profile option from the left navigation bar and make the applicable selections.

Affected Catalog Part Numbers (CPN)

AT89LS51-16PU

AT89S51-24PU

AT89LS52-16PU

AT89S52-24PU